

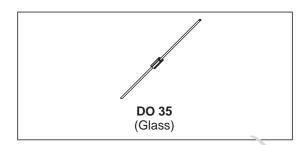
SMALL SIGNAL SCHOTTKY DIODE

DESCRIPTION

Metal to silicon junction diode featuring high breakdown, low turn-on voltage and ultrafast switching.

Primarly intended for high level UHF/VHF detection and pulse application with broad dynamic

Matched batches are available on request.



ABSOLUTE RATINGS (limiting values)

Symbol	Parameter	Value	Unit
V_{RRM}	Repetitive Peak Reverse Voltage	70	V
I _F	Forward Continuous Current*	5	mA
I _{FSM}	Surge non Repetitive Forward Current*	50	mA
T _{stg} T _j	Storage and Junction Temperature Rang	- 65 to 200 - 65 to 200	°C
TL	Maximum Lead Temperature for Solderin 4mm from Case	230	°C

THERMAL RESISTANCE

Symbol	Test Conditions	Value	Unit
R _{th(j-a)}	Junction-ambient*	400	°C/W

ELECTRICAL CHARACTERISTICS

STATIC CHARACTERISTICS

Symbol	Test Conditions	Min.	Тур.	Max.	Unit
V_{BR}	$T_{AIIID} = 25^{\circ}CI_{R} = 10\mu A$	70			٧
V _F * *	T _{amb} = 25°CI _F = 1mA			0.41	V
5	$T_{amb} = 25^{\circ}CI_F = 15mA$			1	
I _R * *	$T_{amb} = 25^{\circ}CV_R = 50V$			0.2	μΑ

DYNAMIC CHARACTERISTICS

Symbol	Test Conditions	Min.	Тур.	Max.	Unit
С	$T_{amb} = 25$ °C $V_R = 0$ V $f = 1$ MHz			2	pF
τ	T _{amb} = 25°CI _F = 5mA Krakauer Method	·		100	ps

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^{*} On infinite heatsink with 4mm lead length
** Pulse test: $t_{p \cdot 0} 300 \mu s \cdot \delta < 2\%$.
Matched batches available on request. Test conditions (forward voltage and/or capacitance) according to customer specification.

Fig. 1: Forward current versus forward voltage at low level (typical values).

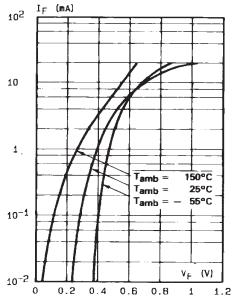


Fig. 2: Capacitance C versus reverse applied voltage V_R (typical values).

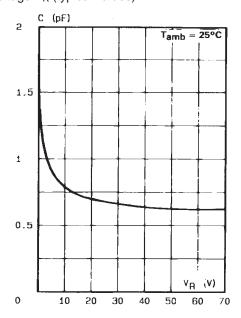


Fig. 3: Reverse current versus ambient temperature.

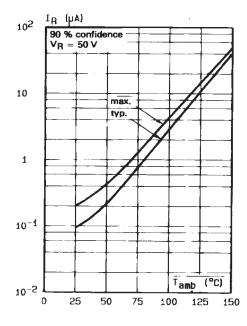
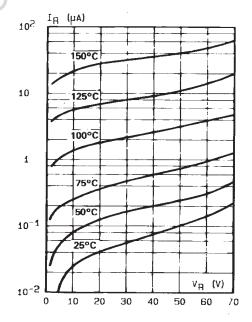


Fig. 4: Reverse current versus continuous reverse voltage (typical values).

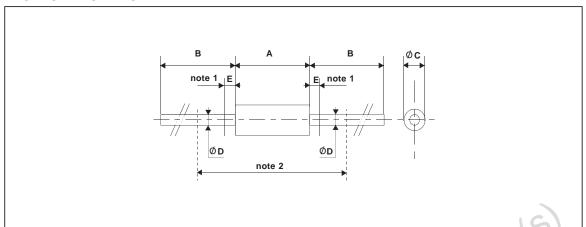


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Cooling method: by convection and conduction

Marking: clear, ring at cathode end.

PACKAGE MECHANICAL DATA



DIMENSIONS			SIONS		NOTES	
REF. Millimeters Inches		hes	Odice			
	Min.	Max.	Min.	Max.	PKO	
Α	3.050	4.500	0.120	0.117	1 - The lead diameter Ø D is not controlled over zone E	
В	12.7		0.500		2 - The minimum axial lengh within which the device may be	
ØC	1.530	2.000	0.060	0.079	placed with its leads bent at right angles is 0.59"(15 mm)	
ØD	0.458	0.558	0.018	0.022	Ob	
Е		1.27		0.050		
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